

Features

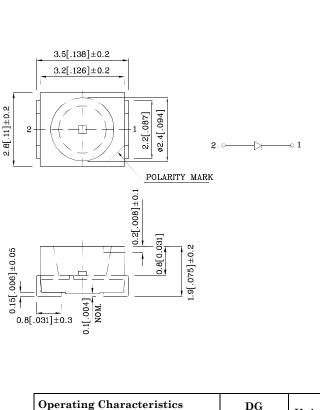
- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- Black case.
- RoHS compliant.



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25(0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)	DG (InGaN)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA
Power Dissipation	PD	123	mW
Operating Temperature	ТА	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	C



Operating Characteristic (TA=25°C)	DG (InGaN)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	3.3	V
Forward Voltage (Max.) (IF=20mA)	VF	4.1	V
Reverse Current (Max.) (VR=5V)	IR	50	uA
Wavelength of Peak Emis- sion (Typ.) (IF=20mA)	λΡ	515	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	30	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

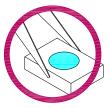
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 0 1/2
				min.	typ.		
XZDG45SB	Green	InGaN	Water Clear	170	248	515	120°
Published Date : I	DEC 30,2010	Drav	ving No : XDSB5031	V2	Chec	ked : B.L.LIU	P. 1/5



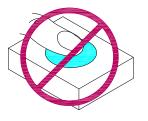
Handling Precautions

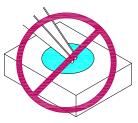
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



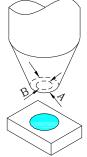


3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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